



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

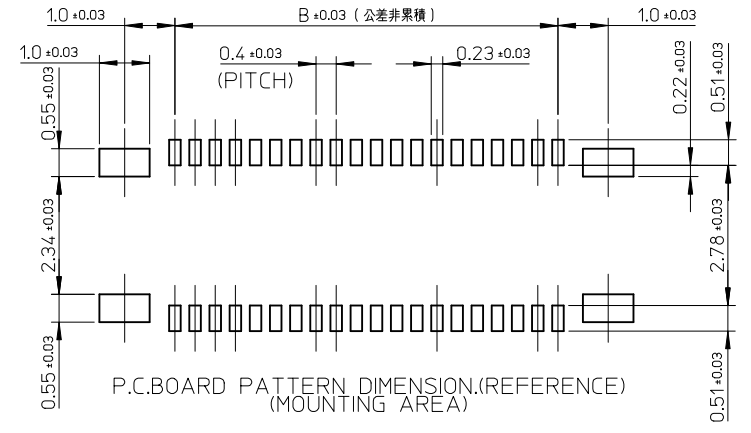
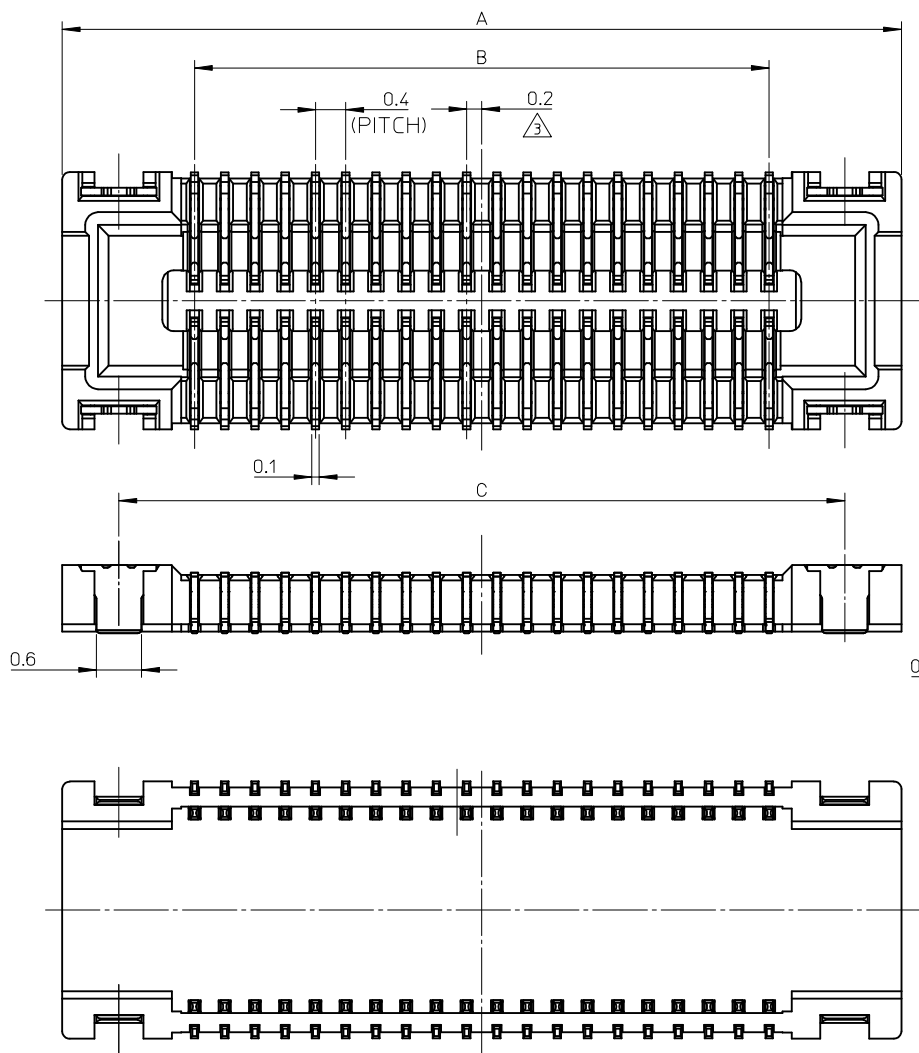
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10 9 8 7 6 5 4 3 2 1



15.6	13.6	17.1	501591-7011	501591-7010	70
12.4	10.4	13.9	501591-5411	501591-5410	54
11.6	9.6	13.1	501591-5011	501591-5010	50
10.4	8.4	11.9	501591-4411	501591-4410	44
9.6	7.6	11.1	501591-4011	501591-4010	40
8.4	6.4	9.9	501591-3411	501591-3410	34
7.6	5.6	9.1	501591-3011	501591-3010	30
6.8	4.8	8.3	501591-2611	501591-2610	26
6.4	4.4	7.9	501591-2411	501591-2410	24
6.0	4.0	7.5	501591-2211	501591-2210	22
5.6	3.6	7.1	501591-2011	501591-2010	20
4.0	2.0	5.5	501591-1211	501591-1210	12
3.6	1.6	5.1	501591-1011	501591-1010	10
C	B	A	EMBOSSED TAPE PACKAGE	MATERIAL NO.	CIRCUIT
			ORDER No.		

REVISED EC NO: J2008-3370 DRW:KSE10 2008/06/17 CHK:D:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY TASAKAWA	DATE 2006/07/10	TITLE 0.4MM PITCH B/B CONN. H=0.9 W=3.4 REC ASSY		
	10 OVER 30 UNDER	± 0.25	CHECKED BY MSASAO	DATE 2006/07/10	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2006/07/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501591-005	SHEET NO. 1 OF 2
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記 NOTES

1. 使用材料 MATERIAL

ハウジング：液晶ポリマー (LCP) ガラス充填 UL-94V-0 (黒)
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:BLACK)

ターミナル：りん青銅 (t=0.1)
 TERMINAL : PHOSHOR BRONZE (t=0.1)

金具：りん青銅 (t=0.1)
 FITTING NAIL : PHOSHOR BRONZE (t=0.1)

2. メッキ仕様 PLATING

ターミナル TERMINAL

金メッキ 0.1マイクロメートル以上 (コンタクト部)
 GOLD 0.1 MICROMETER MINIMUM (CONTACT AREA)

金メッキ 0.05マイクロメートル以上 (テール部)
 GOLD 0.05 MICROMETER MINIMUM (TAIL AREA)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
 UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM

金具 FITTING NAIL

錫メッキ :1.0マイクロメートル以上
 TIN PLATING :1.0 MICROMETER MINIMUM

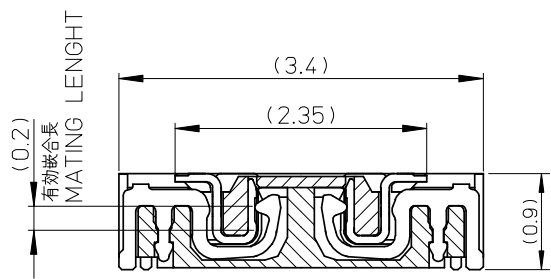
下地メッキ :ニッケル 1.0マイクロメートル以上
 UNDER PLATING :NICKEL 1.0 MICROMETER MINIMUM

△ (全極数/2)=偶数の場合に適用
 APPLY FOR (CIRCUIT/2)=EVEN

4. 嵌合相手 : 501594-**10 シリーズ
 WITH MATE : 501594-**10 SERIES

5. テール及び金具の平坦度は、0.1以下
 TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM

6. ELV AND RoHS COMPLIANT.

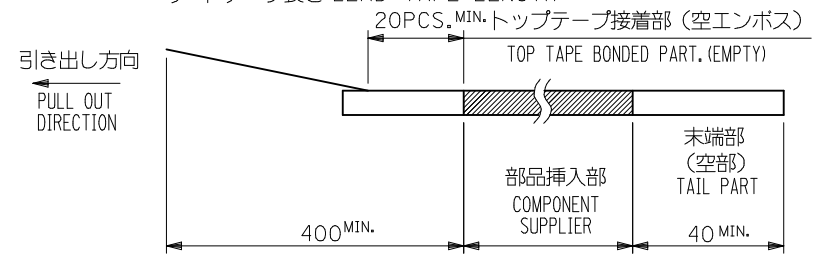
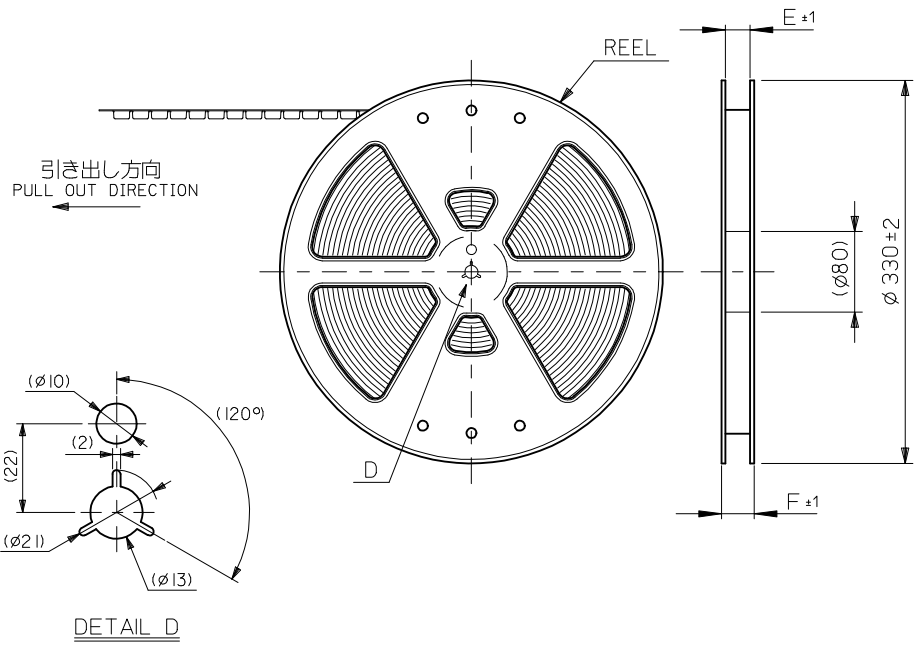


嵌合断面図 (参考)
 MATED DRAWING

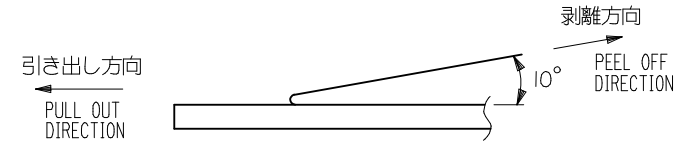
REVISED EC NO: J2008-3370 DRW:KSETO 2008/06/17 CHK:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25 T REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY TASAKAWA	DATE 2006/07/10	TITLE 0.4MM PITCH B/B CONN. H=0.9 W=3.4 REC ASSY			
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2006/07/10				
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2006/07/10	MOLEX INCORPORATED			
	ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-501591-005		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量： 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



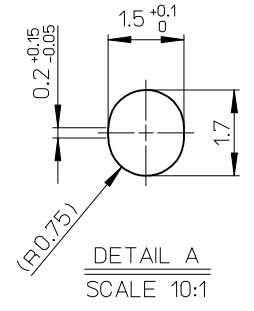
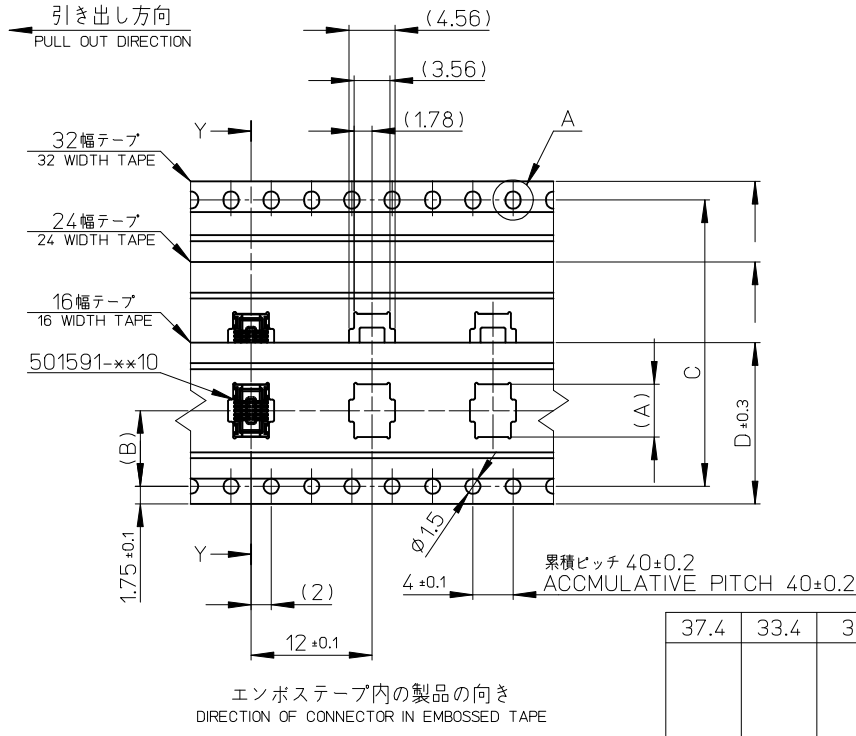
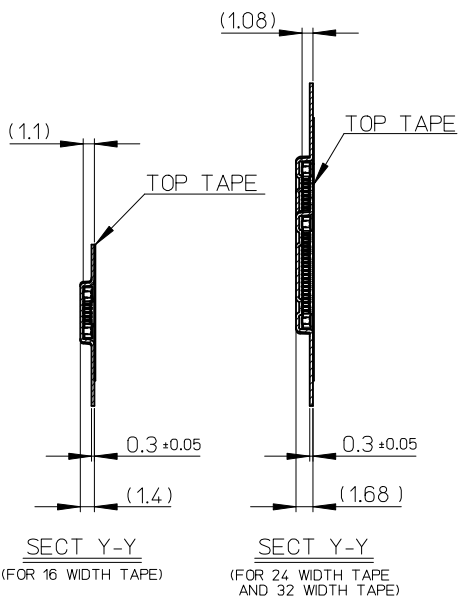
- トップテープの剥離強度： JES-59 参照
剥離方向は下図参照。
PEELING OFF STRENGTH OF TOP TAPE : REFER TO JES-59
PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ホリスチレン (POLYSTYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYLENE (PS) <RECYCLE MATERIAL CONTAINED>

6.ELV AND RoHS COMPLIANT.

REVISED EC NO: J2008-3370 DRW:KSETO 2008/06/17 CHKD:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	501591-**11	MODEL NO.
	10 UNDER	± 0.2	DRAWN BY TASAKAWA	DATE 2006/07/10	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER	± 0.25	CHECKED BY MSASAO	DATE 2006/07/10	0.4 B-TO-B CONN. REC ASSY (HGT=0.9) EMBSTP PKG	
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2006/07/10	MOLEX INCORPORATED	
REV	DESCRIPTION	ANGULAR ± 3 °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-501591-006	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



37.4	33.4	32	28.4	14.2	17.26	501591-7011	70
					14.06	501591-5411	54
					13.26	501591-5011	50
					12.06	501591-4411	44
					11.26	501591-4011	40
29.4	25.4	24	—	11.5	10.06	501591-3411	34
					9.26	501591-3011	30
					8.46	501591-2611	26
					8.06	501591-2411	24
					7.66	501591-2211	22
					7.26	501591-2011	20
21.4	17.4	16	—	7.5	5.66	501591-1211	12
					5.26	501591-1011	10
F	E	D	C	(B)	(A)	MATERIAL No.	極数 CKT

REVISED EC NO: J2008-3370 DRW:KSE10 2008/06/17 CHK:D:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		501591-**11 MODEL No.	
	10 UNDER	± 0.2	DRAWN BY TASAKAWA		DATE 2006/07/10	TITLE			
	10 OVER 30 UNDER	± 0.25	CHECKED BY MSASAO		DATE 2006/07/10	0.4 B-TO-B CONN. REC ASSY (HGT=0.9) EMBSTP PKG			
	30 OVER	± 0.3	APPROVED BY MSASAO		DATE 2006/07/10	MOLEX INCORPORATED			
	ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501591-006		2 OF 2			
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					